

1A SURFACE MOUNT GLASS PASSIVATED BRIDGE

RECTIFIER Reverse Voltage - 100 to 1000 V

Forward Current - 1A

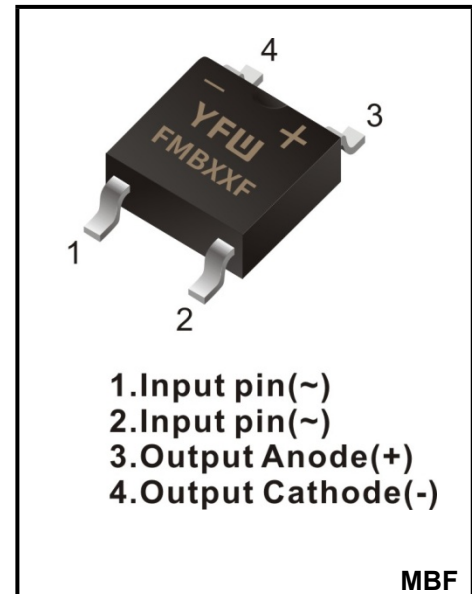
FEATURES

- ◆High current capability
- ◆Low forward voltage drop
- ◆Glass Passivated Chip Junction
- ◆Low power loss, high efficiency
- ◆Lead free in comply with EU RoHS 2011/65/EU directives



MECHANICAL DATA

- ◆Case: MBF
- ◆Terminals: Solderable per MIL-STD-750, Method 2026
- ◆Approx. Weight: 75mg / 0.0026oz



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	FMB1F	FMB2F	FMB4F	FMB6F	FMB8F	FMB10F	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_c = 125^\circ C$	I_o	1						A
Peak Forward Surge Current 8.3 ms Single Half Sine-Wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	35						A
Forward Voltage per element at 1.0A	V_F	1.3						V
Maximum DC Reverse Current @ $T_A=25^\circ C$ at Rated DC Blocking Voltage @ $T_A=125^\circ C$	I_R	5 50						μA
Typical Junction Capacitance (Note1)	C_j	15						pF
Maximum Reverse Recovery Time (Note2)	T_{rr} $T_{rr}(typ)$	500 300						nS
Typical Thermal Resistance (Note3)	$R_{\theta JA}$ $R_{\theta JC}$	80 30						$^\circ C/W$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150						$^\circ C$

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

Fig.1 Average Rectified Output Current Derating Curve

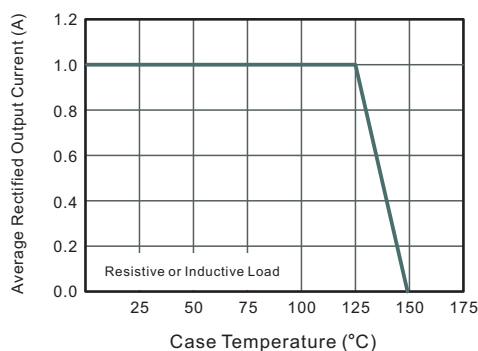


Fig.2 Typical Reverse Characteristics

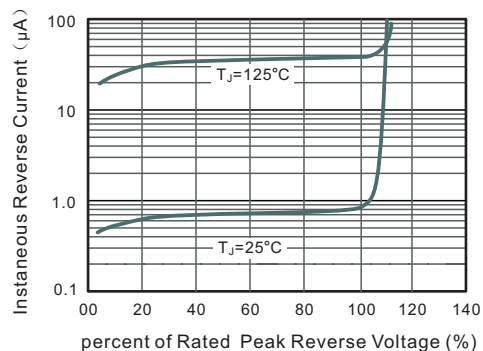


Fig.3 Typical Instantaneous Forward Characteristics

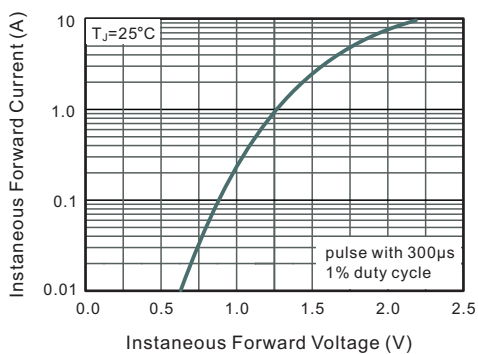


Fig.4 Typical Junction Capacitance

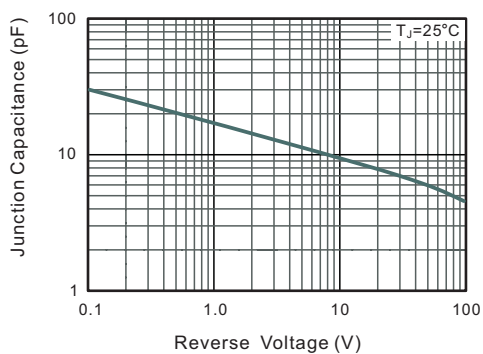
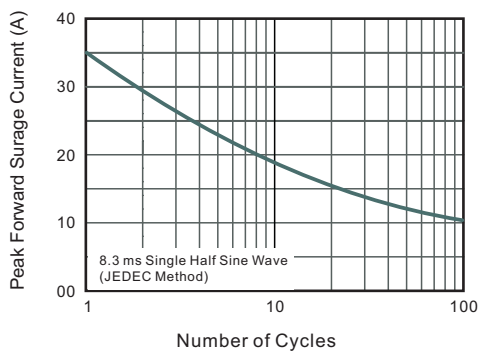


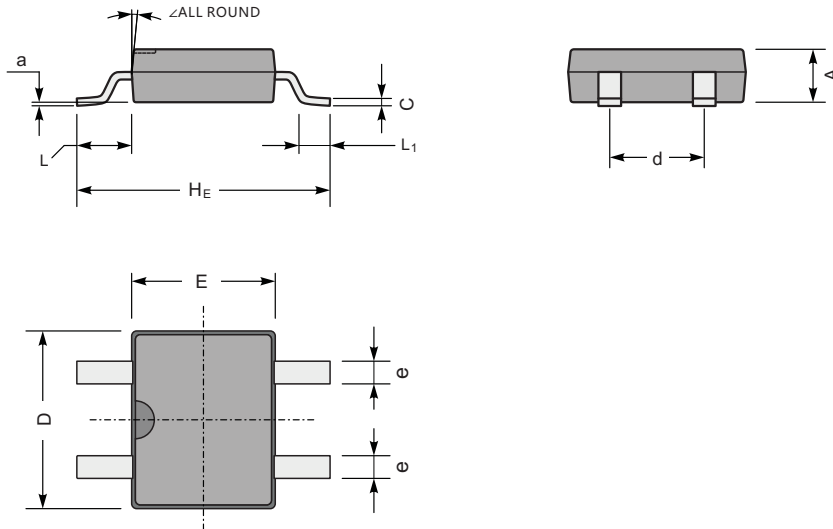
Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



Package Outline

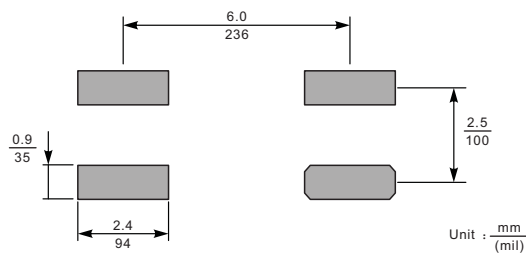
MBF

Plastic surface mounted package; 4 leads



UNIT		A	C	D	E	H _E	d	e	L	L ₁	a	∠
mm	max	1.6	0.22	5.0	4.1	7.0	2.7	0.8	1.7	1.1	0.2	7°
	min	1.2	0.15	4.5	3.6	6.4	2.3	0.5	1.3	0.5	—	
mil	max	63	8.7	197	161	276	106	31	67	43	8	
	min	47	5.9	177	142	252	91	20	51	20	—	

The recommended mounting pad size



Summary of Packing Options

Package	Packing Description	Packing Quantity	Industry Standard
MBF	Tape/Reel, 13" reel	5000	EIA-481-1